JSCJ

MSDS Report

Report NO.: MOS-MG02053000259

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJ2102A
Package Type :	SOT-323

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Die	Silicon	7440-21-3	100.00%	0.32%
Lead Frame	Si	7440-21-3	0.01%	45.3%
	Ni	7440-02-0	0.70%	
	Fe	7439-89-6	0.06%	
	Cu	7440-50-8	97.10%	
	Sn	7440-31-5	1.00%	
	Zn	7440-66-6	0.52%	
	P	7723-14-0	0.20%	
	Ag	7440-22-4	0.41%	
EPOXY	Ag	7440-22-4	70%	0.47%
	epoxy resin	9003-36-5	20%	
	1,4-bis12,3-epoxypropoxy	2425-79-8	8%	
	dapsone	80-08-0	2%	
Wire	Copper	7440-50-8	99.99%	1.42%
	other	/	0.01%	
Mold Compound	Epoxy Resin	29690-82-2	15.00%	51.78%
	Phenol Resin	9003-35-4	7.90%	
	Silica(Amorphous)	60676-86-0	70.00%	
	Metal Hydroxide	Trade Secret	6.90%	
	Carbon Black	1333-86-4	0.01%	
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Plating	Sn	7440-31-5	99.99%	0.69%
	Other	NA	0.01%	